



Nontraditional Applications of Polyethylene Glycol and Related Compounds

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

Polyethylene Glycol (PEG) and related compounds such as PEG related surfactants are traditionally used as additives in many products. This Special Issue intends to highlight research and development efforts that go beyond these traditional uses of PEG and related surfactants. For example, an increasing body of research has shown that PEG and related surfactants can be effective solvents for chemical synthesis for both organic and inorganic materials. They can also be used as engineering fluids, for example, as heat transfer media. In these applications, PEG and related surfactants are not used as additives but constitute a major component. Therefore, manuscripts on fundamental research that can help in promoting novel applications based on PEG and related surfactants by providing a deeper, molecular-level understanding on these are welcome as well.

I thus invite you to submit your research on these topics, in the form of original research papers, mini-reviews, and perspective articles.

Prof. Dr. Markus M. Hoffmann
Guest Editor





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Editor-in-Chief

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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